


**PHYSICAL DIMENSIONS (mm)**

Part Number	A		B		C		D		E
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Min.	Max.
SMD1812P010TS	4.37	4.73	3.07	3.41	0.75	1.25	0.30	0.25	0.65
SMD1812P014TS	4.37	4.73	3.07	3.41	0.75	1.95	0.30	0.25	0.65
SMD1812P020TS	4.37	4.73	3.07	3.41	0.55	1.00	0.30	0.25	0.65
SMD1812P050TG/S	4.37	4.73	3.07	3.41	0.50	0.75	0.30	0.25	0.65
SMD1812P075TG/S	4.37	4.73	3.07	3.41	0.50	0.75	0.30	0.25	0.65
SMD1812P075TS/24	4.37	4.73	3.07	3.41	0.75	1.55	0.30	0.25	0.65
SMD1812P110TG/S	4.37	4.73	3.07	3.41	0.50	0.75	0.30	0.25	0.65
SMD1812P110TS/15	4.37	4.73	3.07	3.41	0.75	1.25	0.30	0.25	0.65
SMD1812P125TS	4.37	4.73	3.07	3.41	0.75	1.25	0.30	0.25	0.65
SMD1812P150TS	4.37	4.73	3.07	3.41	0.75	1.25	0.30	0.25	0.65
SMD1812P160TG/S	4.37	4.73	3.07	3.41	0.75	1.25	0.30	0.25	0.65
SMD1812P200TS	4.37	4.73	3.07	3.41	0.75	1.55	0.30	0.25	0.65
SMD1812P260TS	4.37	4.73	3.07	3.41	1.45	2.25	0.30	0.25	0.65

**ENVIRONMENTAL SPECIFICATIONS**

Operating/Storage Temperature	-40°C to +85°C
Maximum Device Surface Temperature in Tripped State	125°C
Passive Aging	+85°C, 1000 hours ±5% typical resistance change
Humidity Aging	+85°C, 85%R.H. 1000 hours ±5% typical resistance change
Thermal Shock	MIL-STD-202 Method 107G +85°C/-40°C 20 times -30% typical resistance change
Solvent Resistance	MIL-STD-202, Method 215 No change
Vibration	MIL-STD-883C, Method 2007.1, Condition A No change

**PHYSICAL SPECIFICATIONS**

Terminal Material	Gold-Plated Copper or Solder-Plated Copper (Solder Material: 63/37 SnPb)
Lead Solderability	Meets EIA Specification RS186-9E, ANSI/J-STD-002 Category 3.
Packaging	12mm tape on 7 inch reel per EIA-481-1(equivalent to IEC286, part3) 1000 devices per reel for P260TS 2000 devices per reel for P020TS,P050TS, P075TS& P110TS for the others: 1500 devices per reel.

© Specifications are subject to change without notice.

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